

Appl. No. : 09/844,155
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IN THE CLAIMS:

Please cancel Claims 5 and 6. Please amend Claim 1 as follows:

1. (Amended) A copper alloy suitable for an IC lead pin for a pin grid array provided on a plastic substrate, wherein the copper alloy is selected from the group consisting of:

a copper alloy containing 0.05 to 0.5 wt% of Zn and 0.05 to 0.5 wt% of Mg, with the balance being made of unavoidable impurities and Cu;

a copper alloy containing 0.1 to 1.0 wt% of Sn, with the balance being made of unavoidable impurities and Cu; and

a copper alloy containing 0.1 to 1.0 wt% of Sn and 0.1 to 0.6 wt% of Ag, with the balance being made of unavoidable impurities and Cu;

wherein the copper alloy has conductivity of 50% IACS or more, and tensile stress of 400 MPa or more but 650 MPa or less.

Please add the following new claim:

7. (New) A method of making a wire comprising the steps of:

melt casting a copper alloy containing 2.1 to 2.6 wt% of Fe, 0.05 to 0.2 wt% of Zn, and 0.015 to 0.15 wt% of P, with the balance being made of unavoidable impurities and Cu, wherein the copper alloy has conductivity of 50% IACS or more, and tensile stress of 400 MPa or more but 650 MPa or less;

hot working the alloy;

drawing the alloy; and

heat treating the alloy.

REMARKS

With this amendment, Claims 5 and 6 are canceled, Claim 1 is amended, and Claim 7 has been added. Claims 1-4 and 7 are thus presented for further Examination.